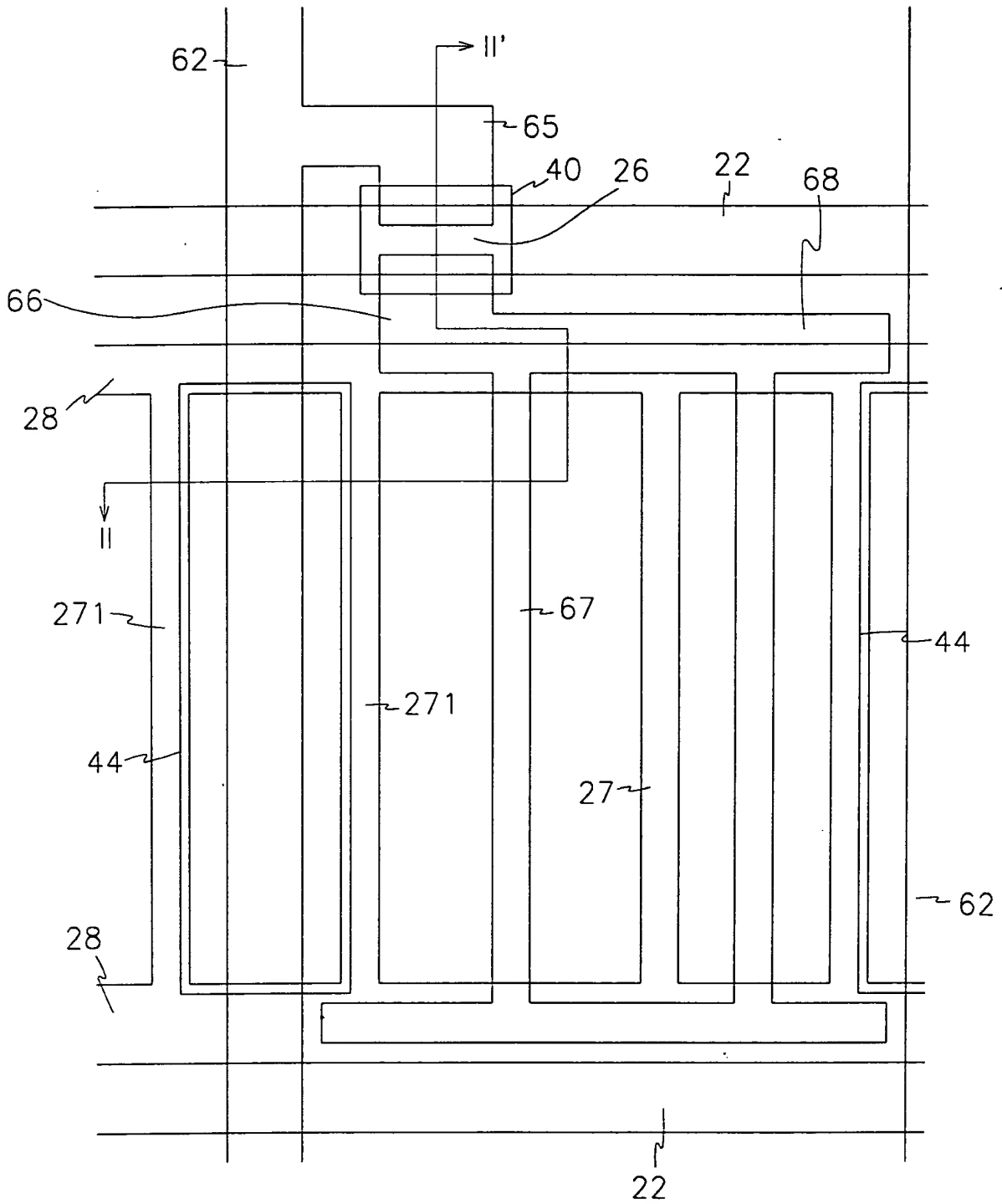


FIG. 1



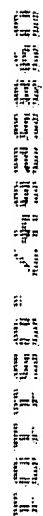


FIG. 2

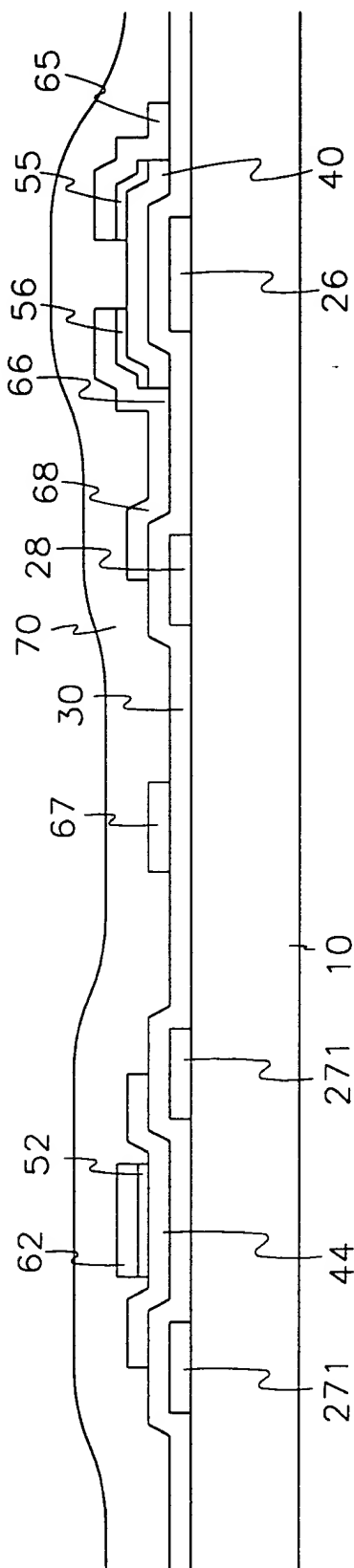


FIG. 3A

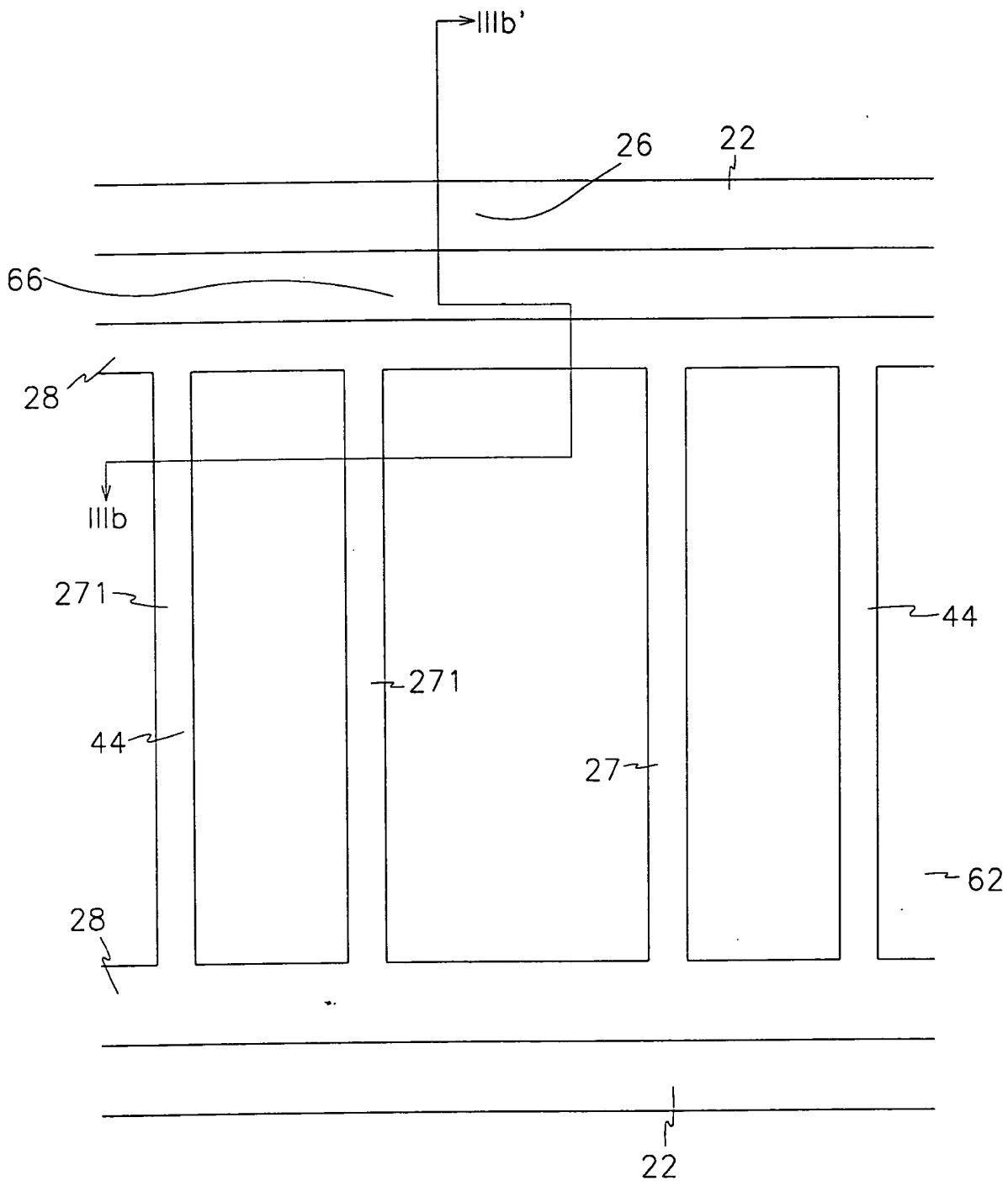


FIG. 3B

FIG. 3B

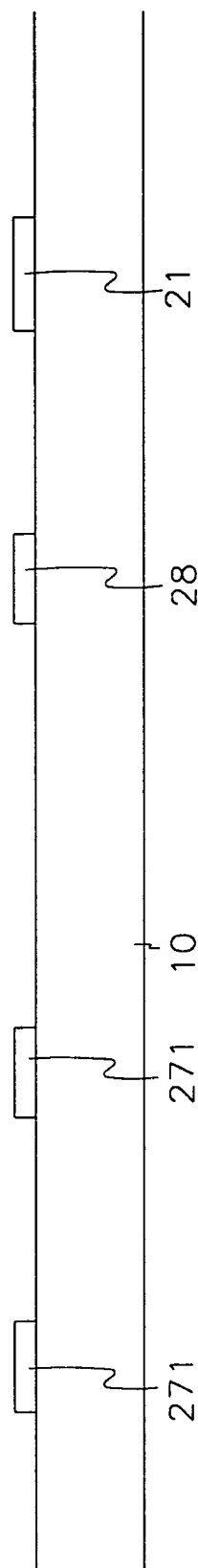


FIG. 4A

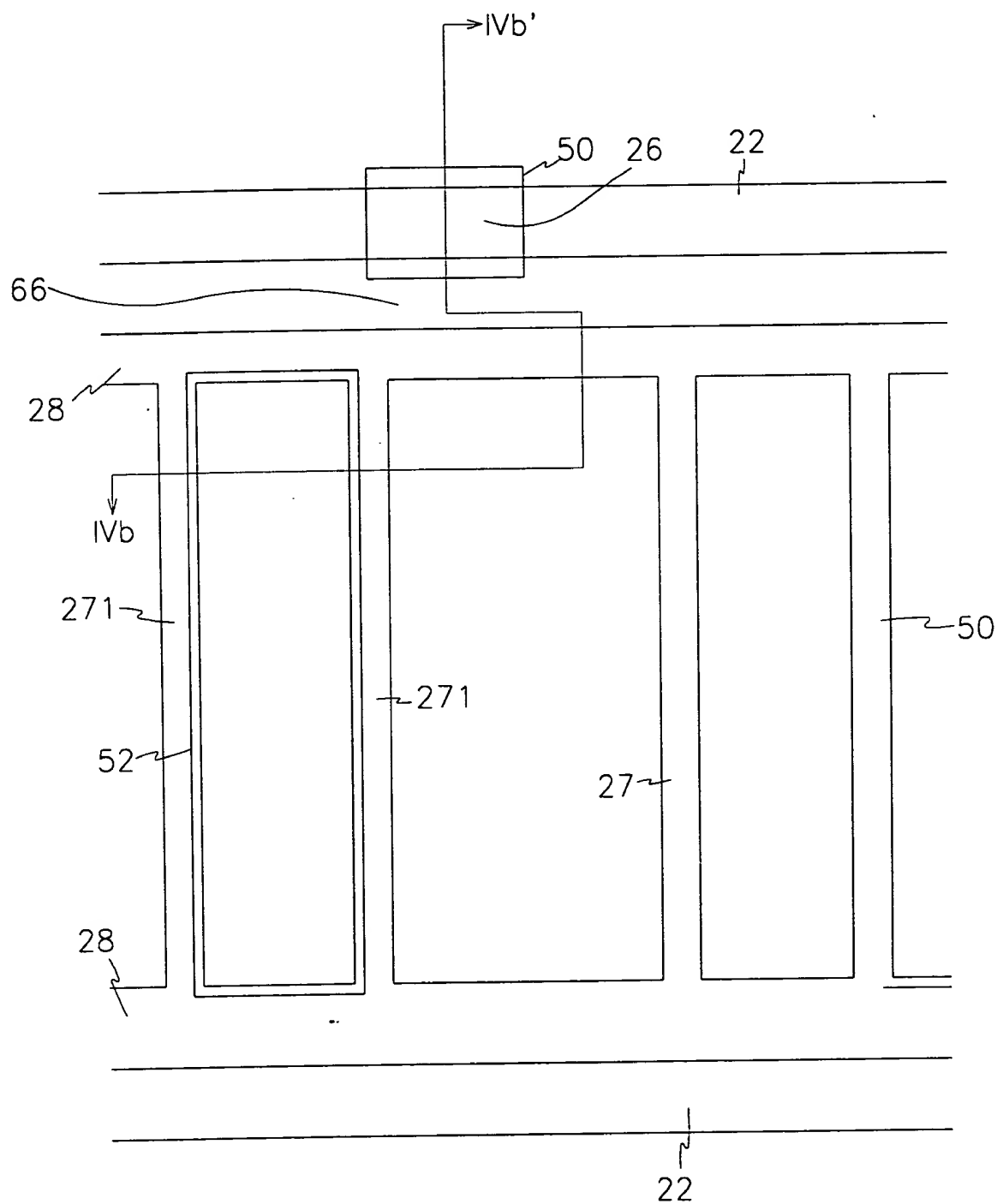
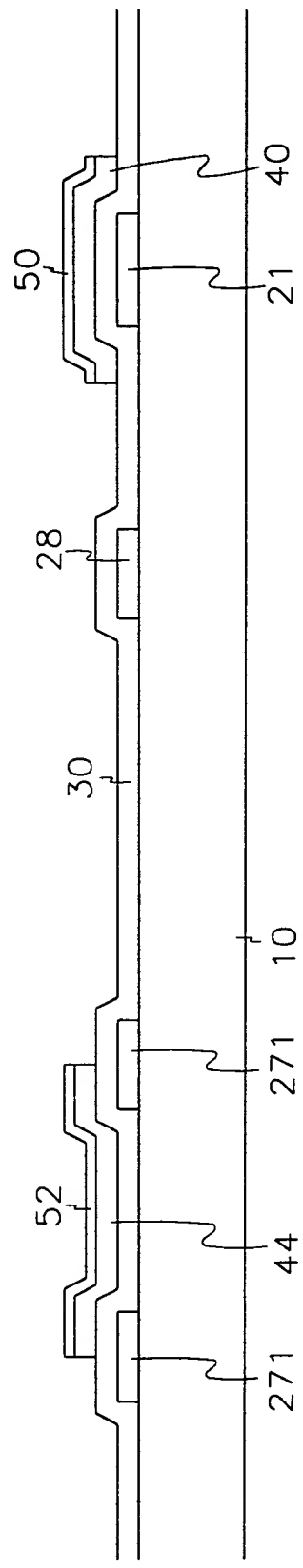


FIG. 4B

FIG. 4B



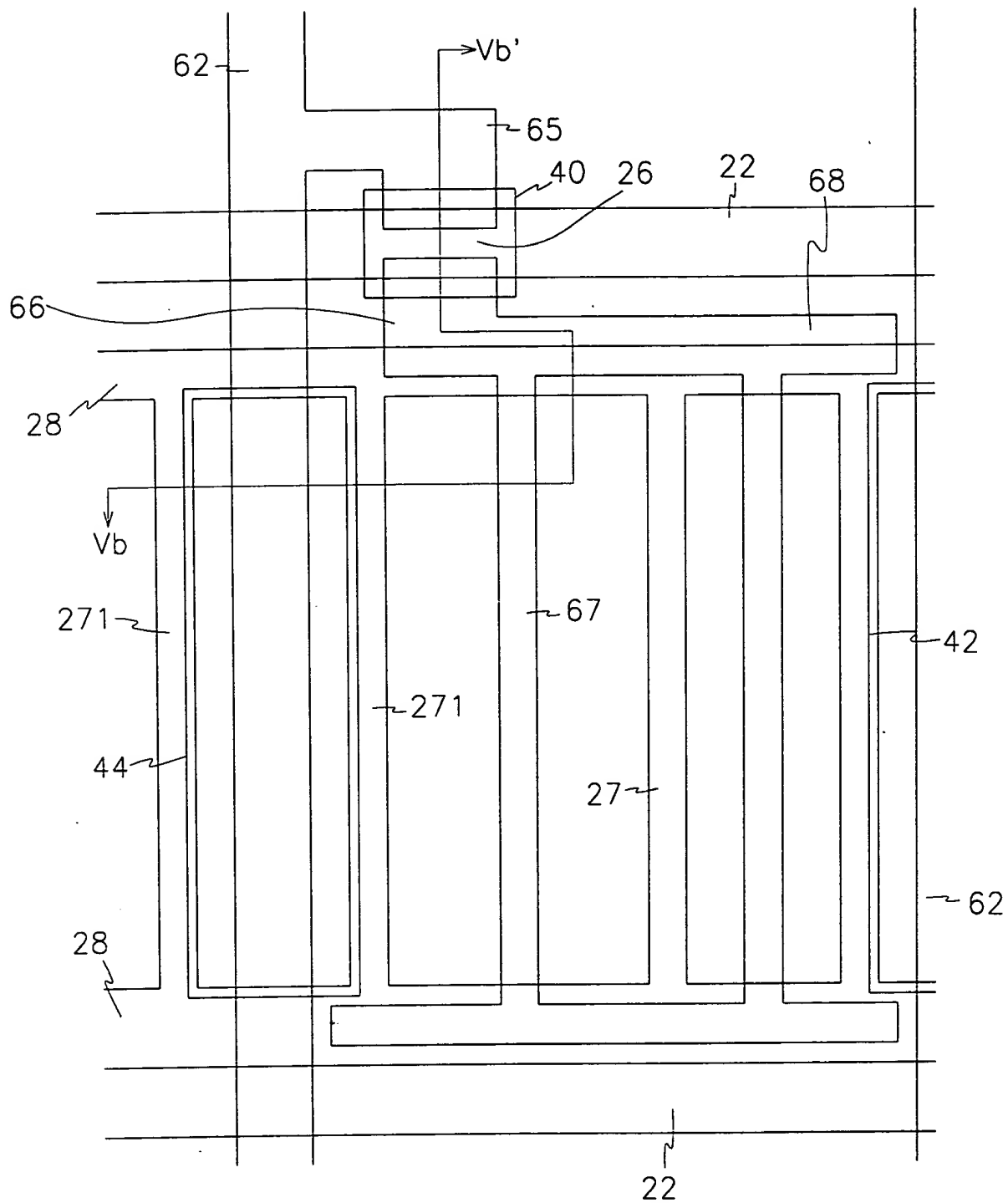


FIG. 5B

FIG. 5B

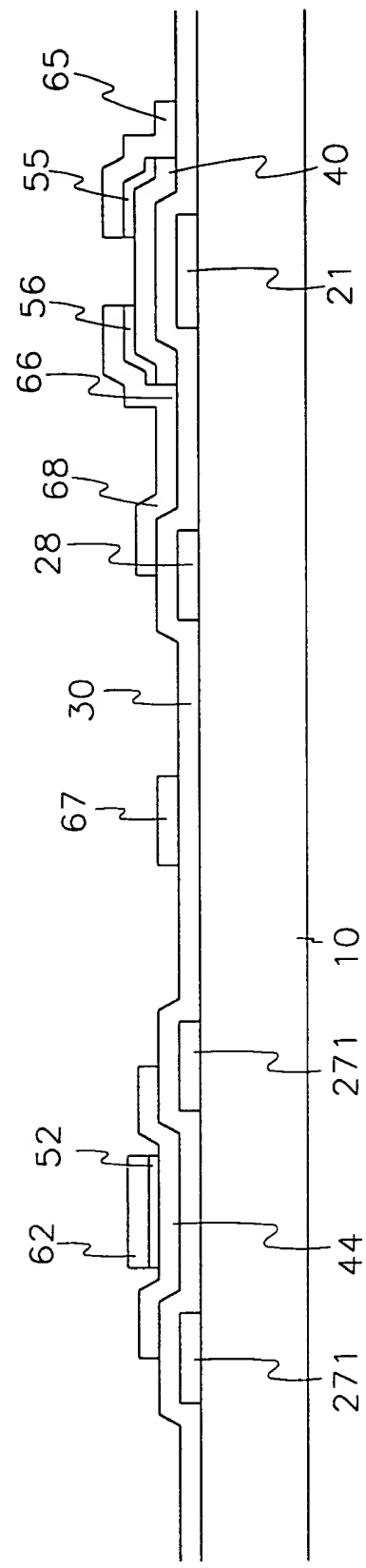




FIG.6

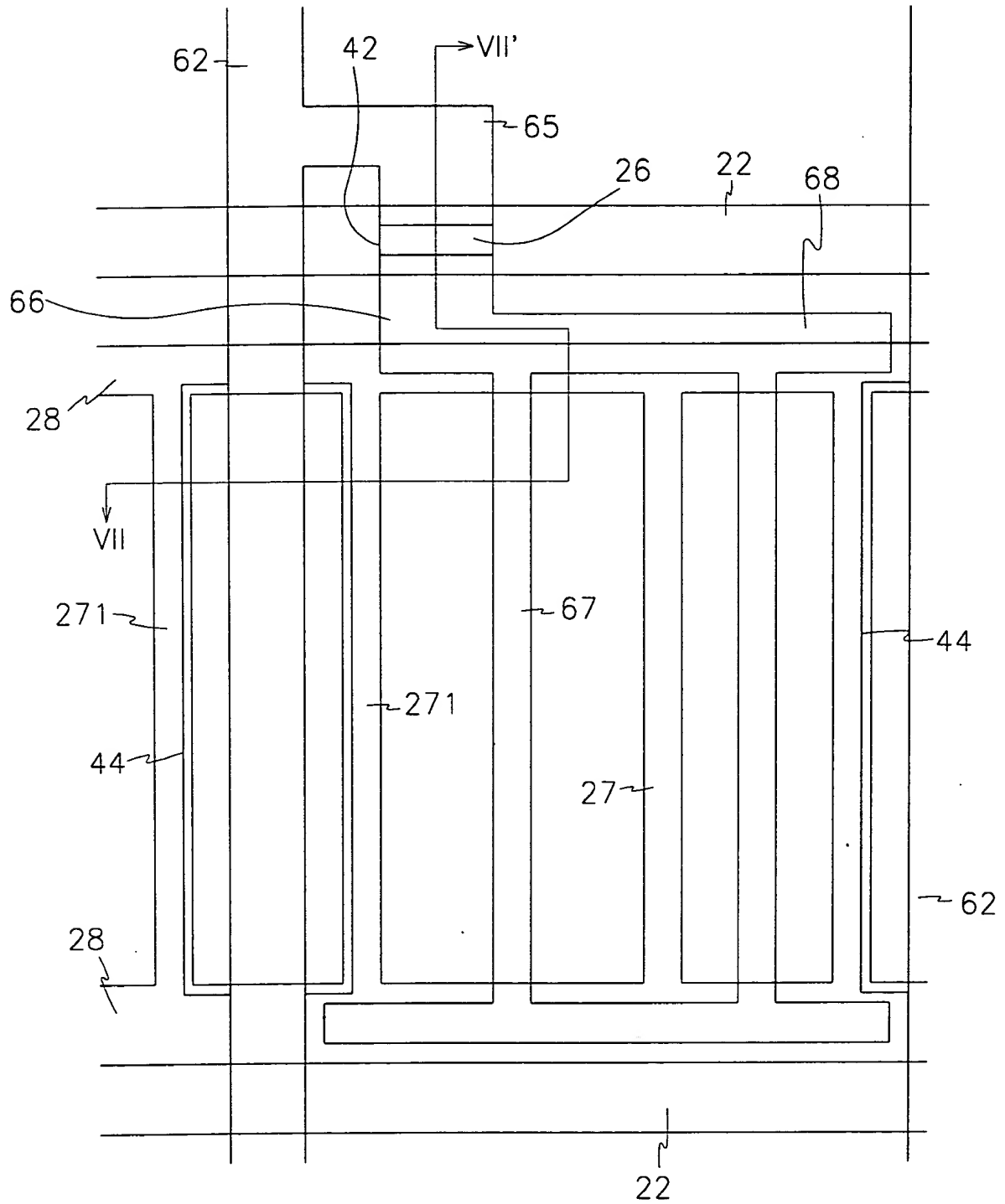


FIG. 7

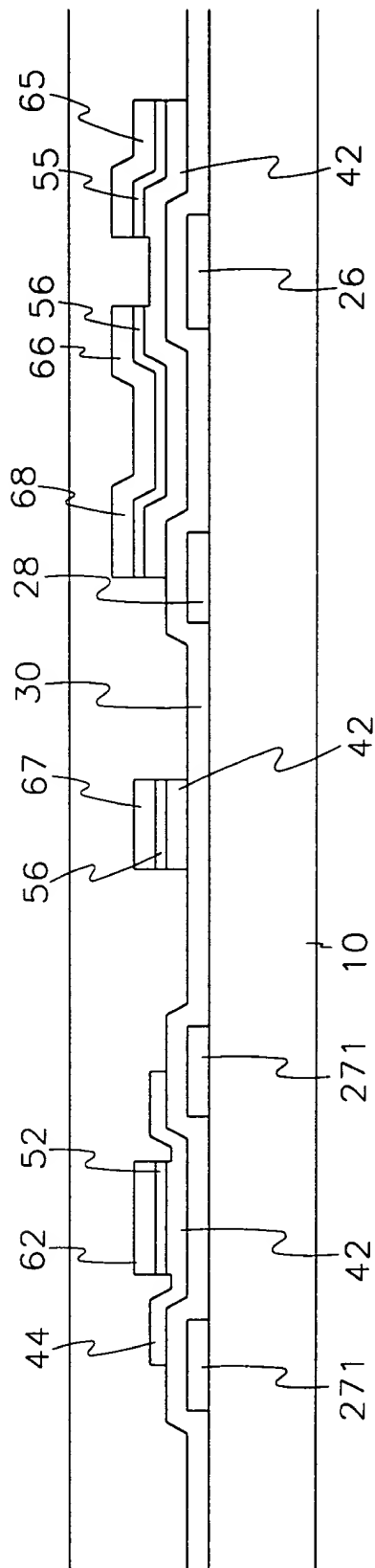


FIG. 8

FIG. 8

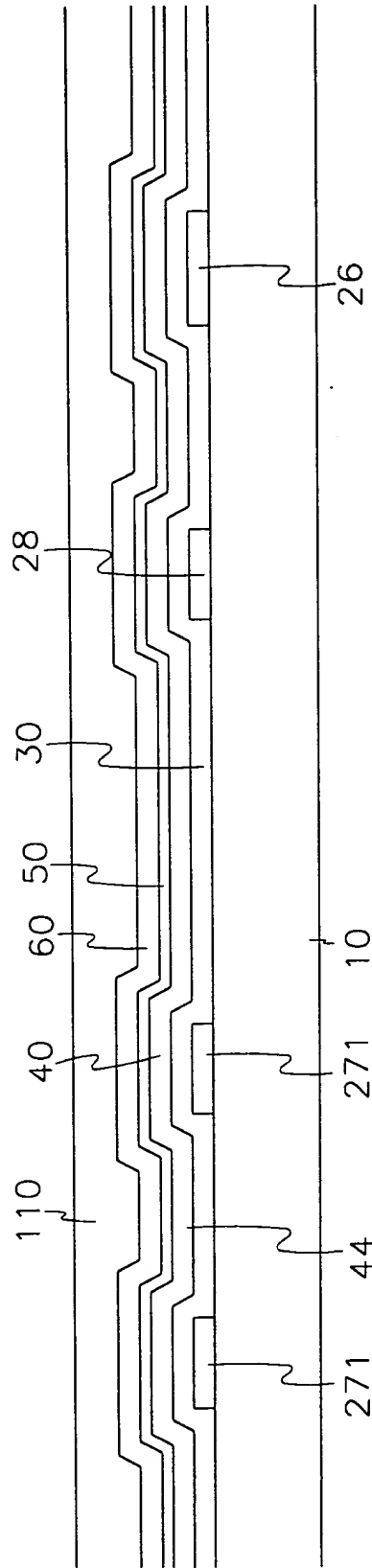


FIG.9

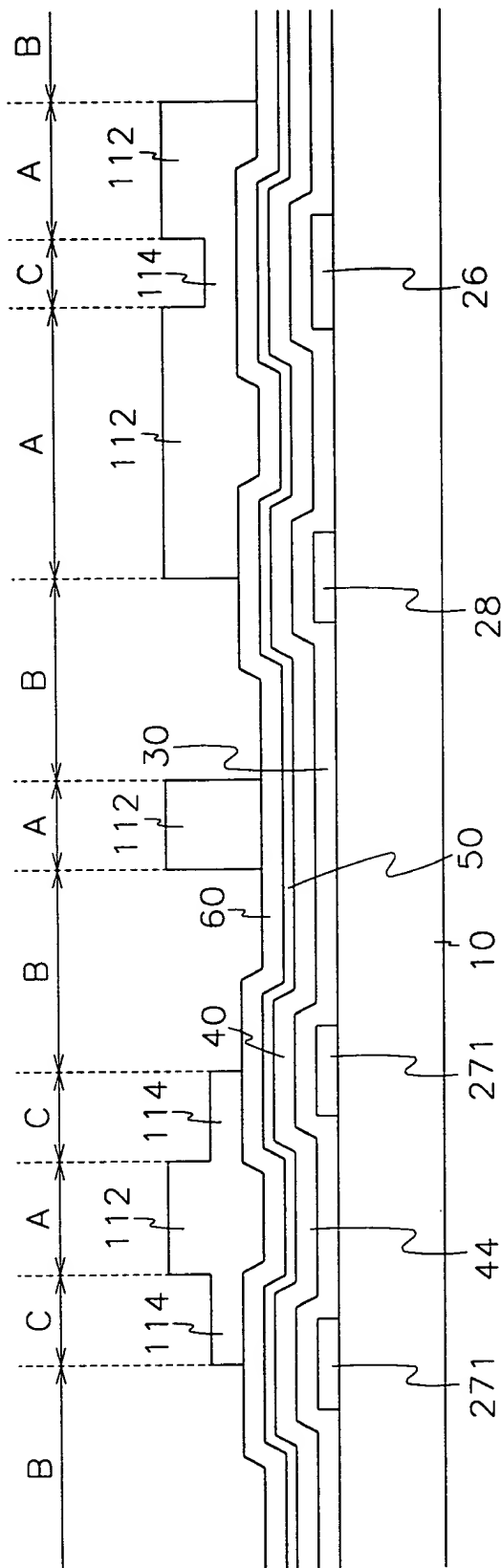
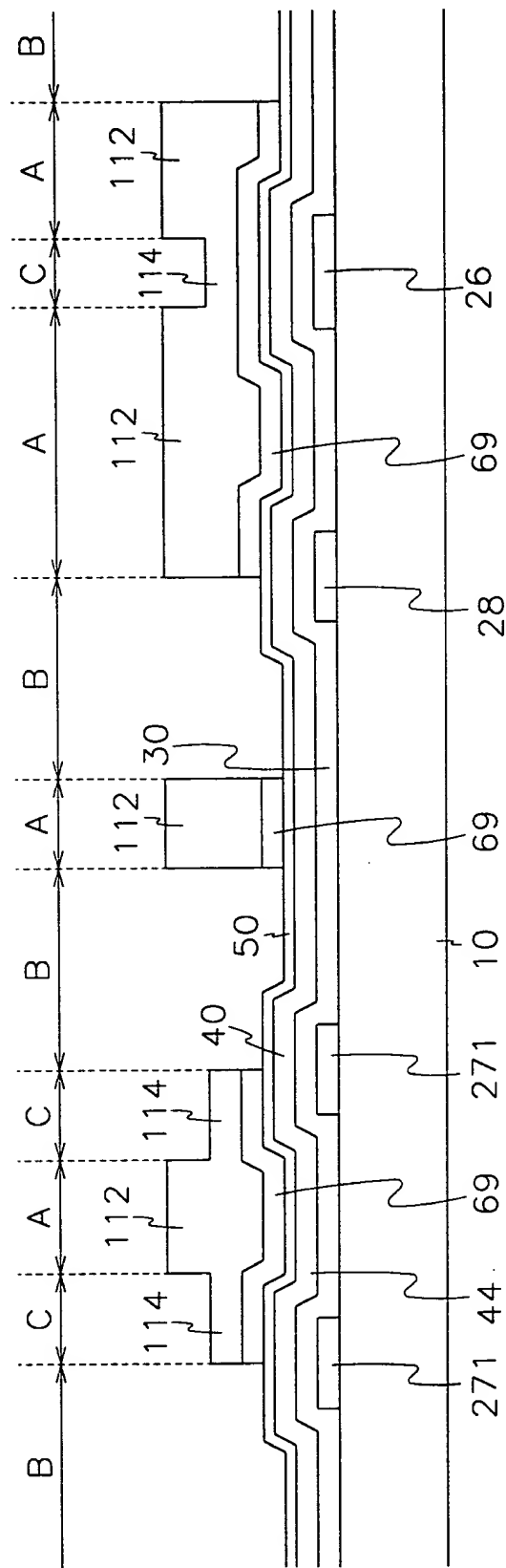


FIG. 10

FIG.10



THIS DRAWING IS NOT TO BE USED FOR REPRODUCTION

FIG.11

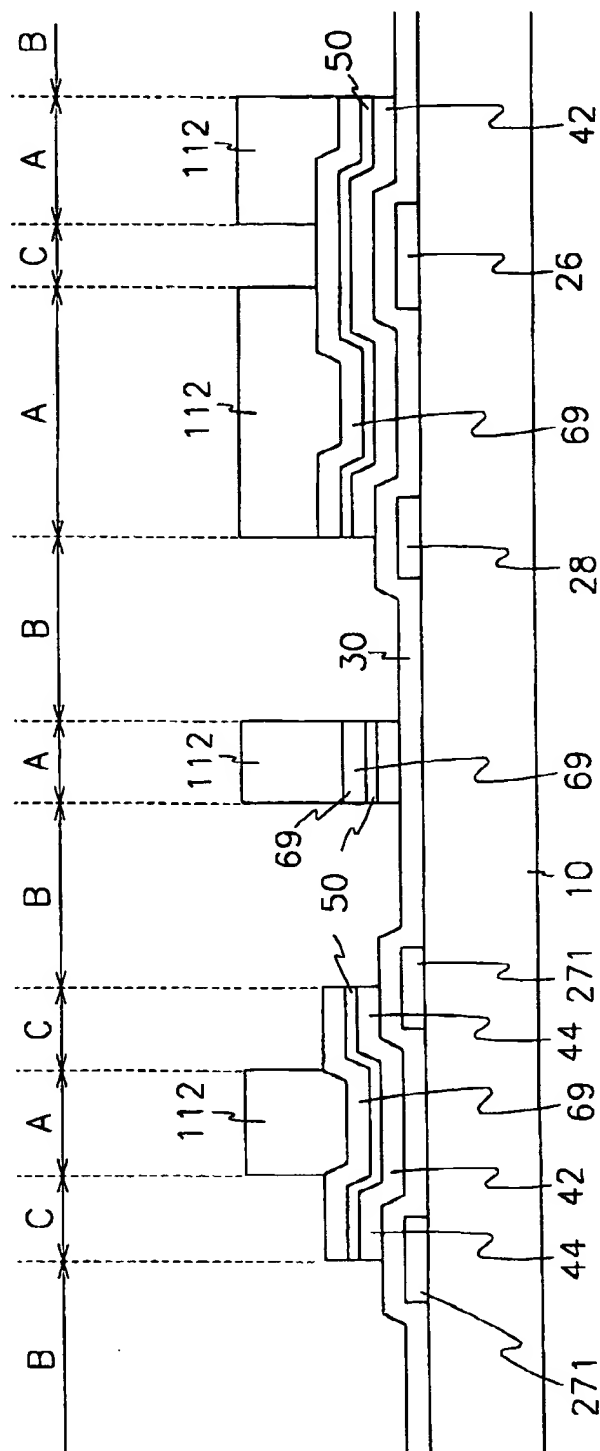


FIG. 12

FIG.12

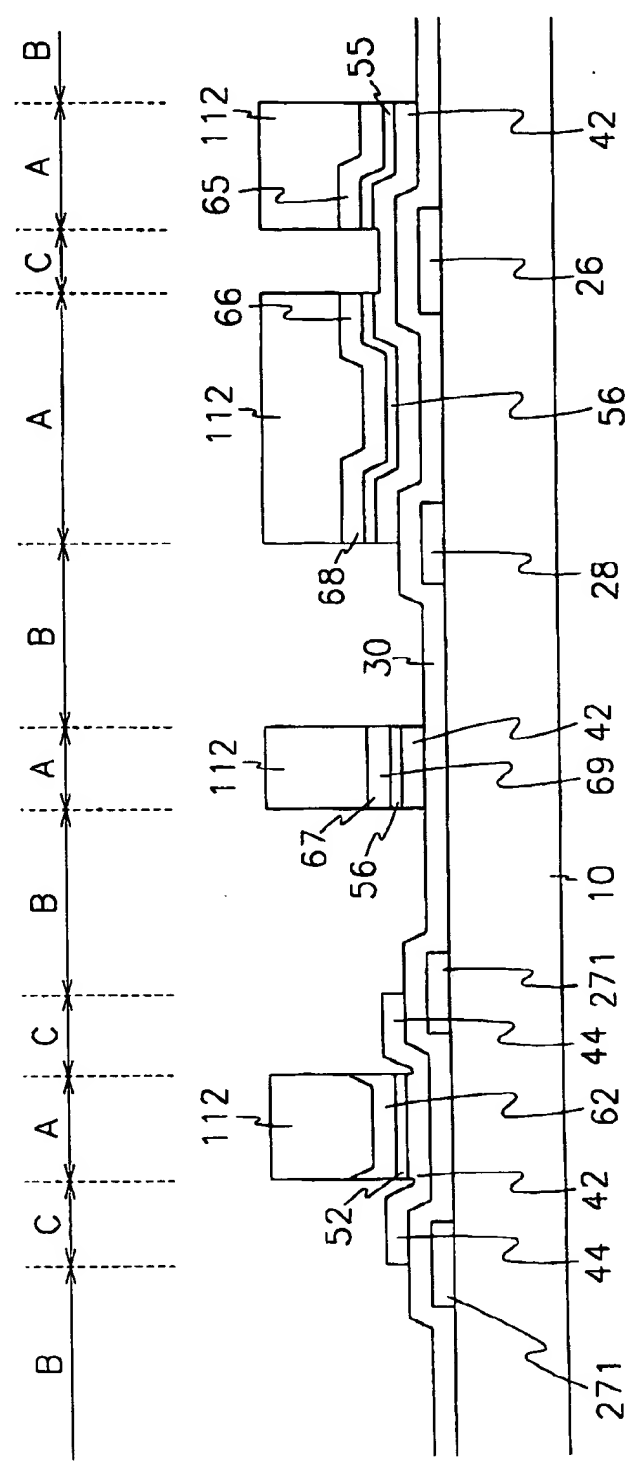


FIG.13

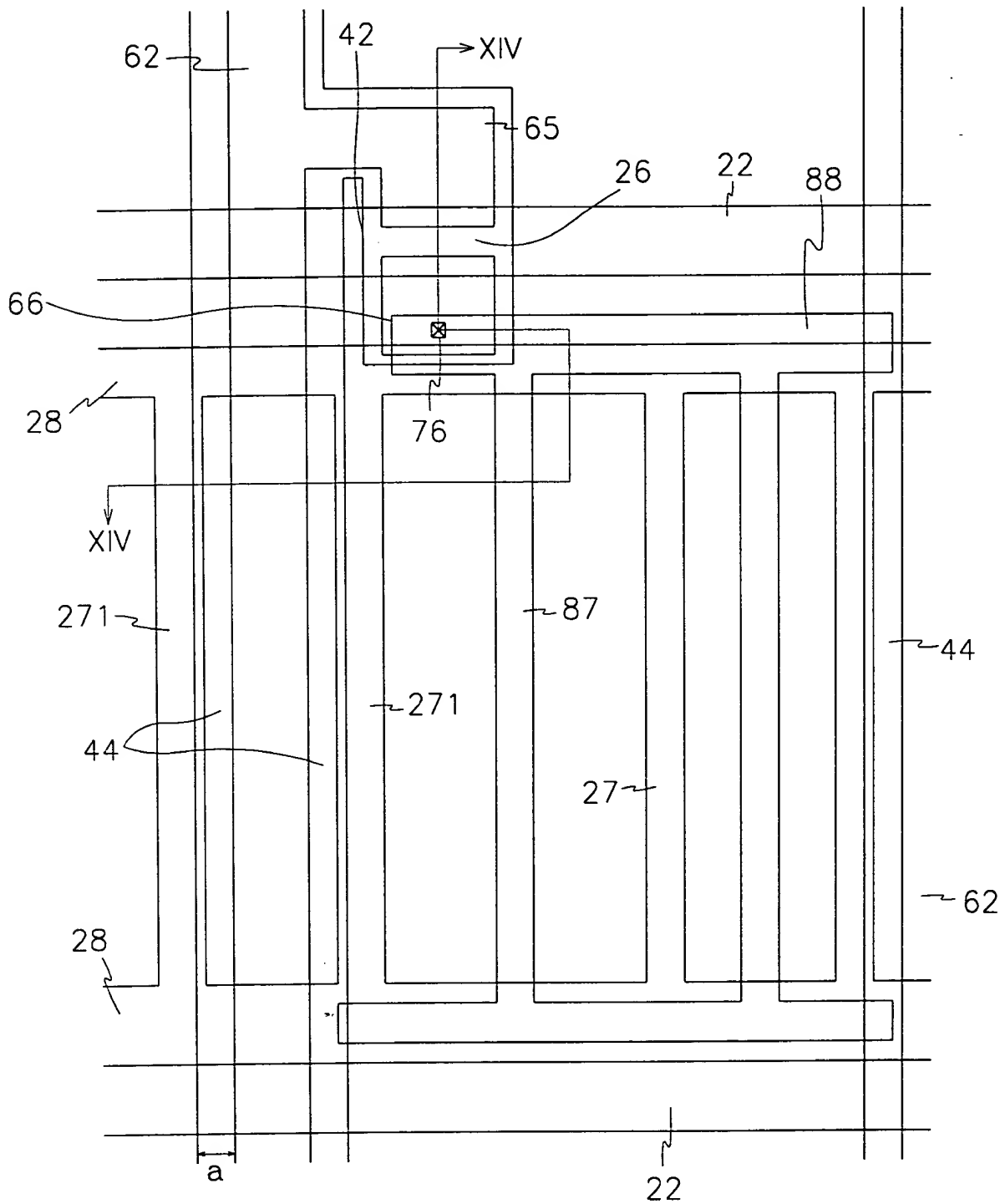




FIG. 14

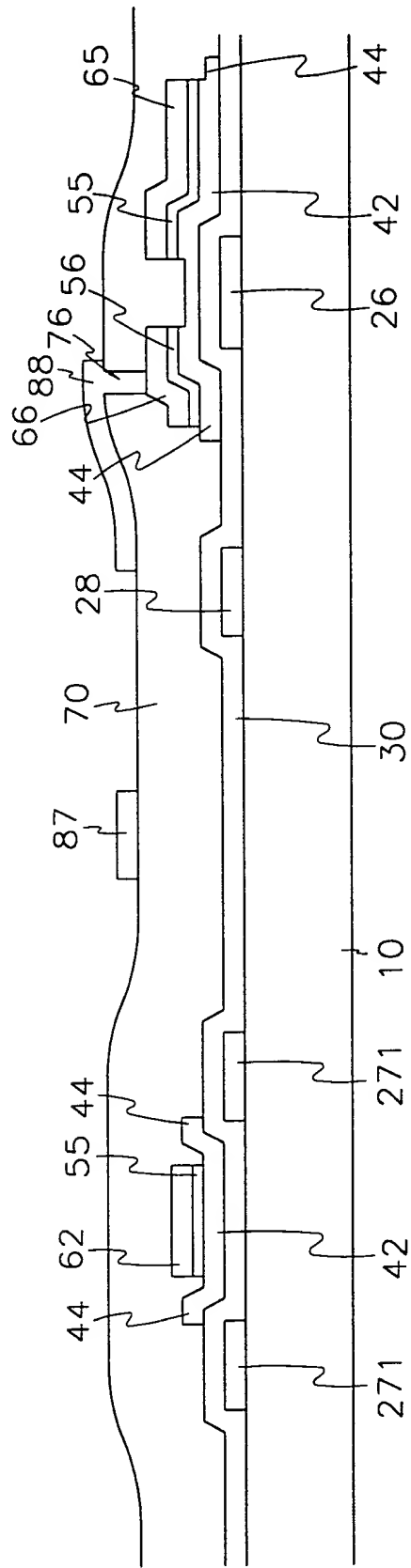
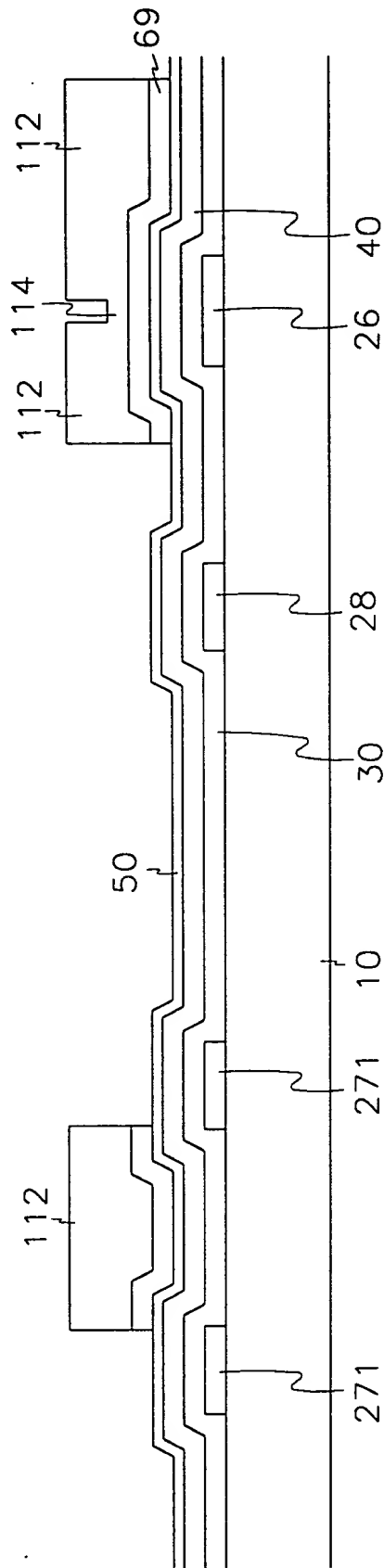


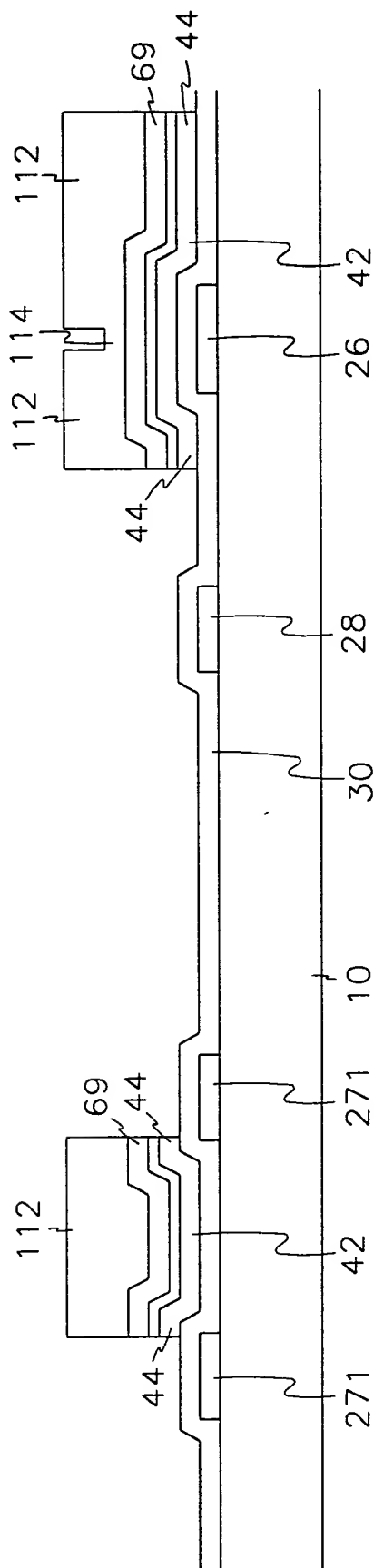
FIG. 15

FIG.15



[illegible]

FIG. 16



This cross-sectional view shows a multi-layered substrate. A central conductive layer (44) is sandwiched between two insulating layers (69). The substrate has a central region (10) and two side regions (271). Conductive pads (26, 28, 30) are located on the central region, and conductive pads (42, 271) are located on the side regions. The side regions (271) are connected to the central region (10) by conductive traces (44). The side regions (271) are also connected to the central region (10) by conductive traces (44). The side regions (271) are also connected to the central region (10) by conductive traces (44).

FIG.18A

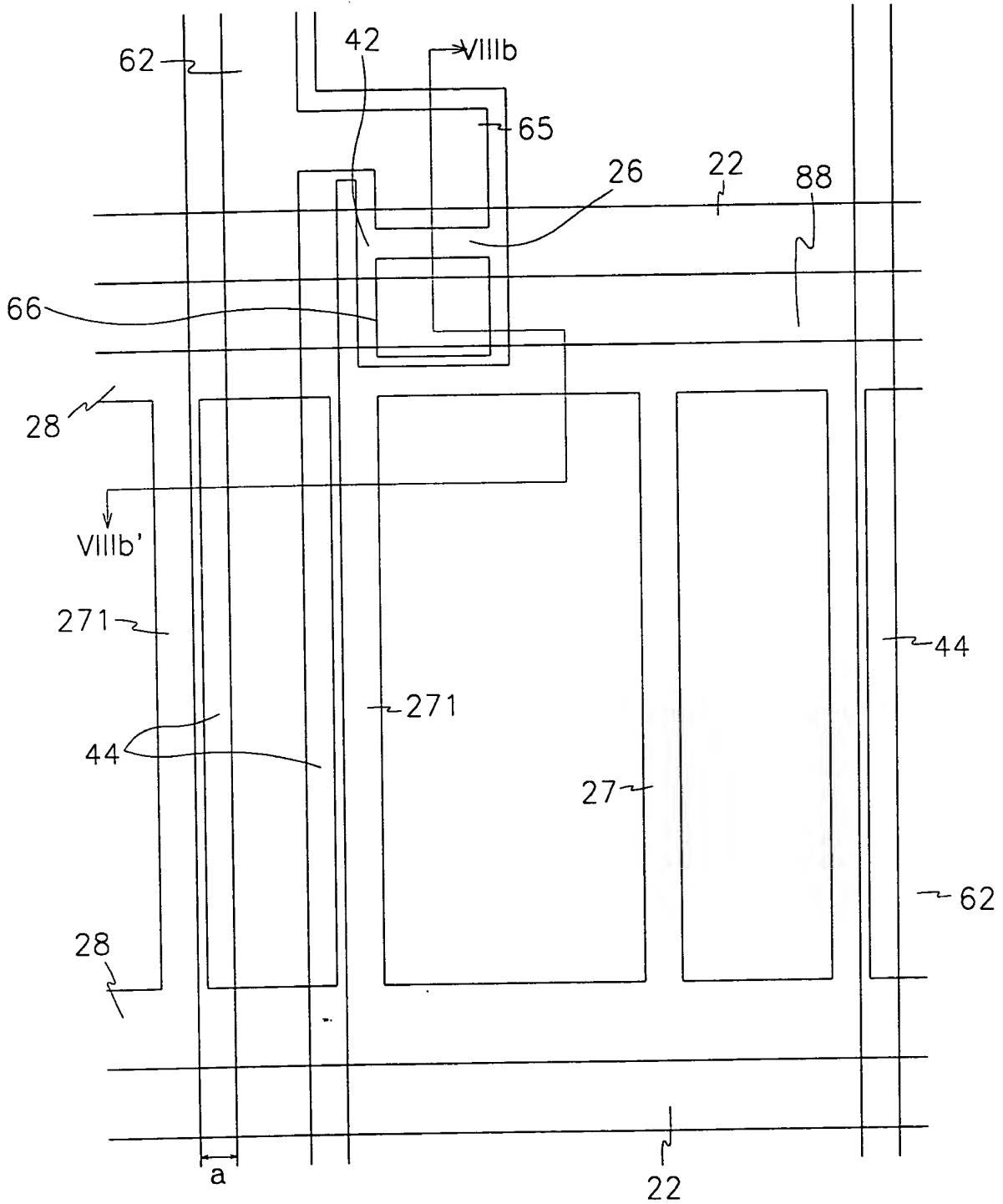


FIG. 18B

FIG. 18B

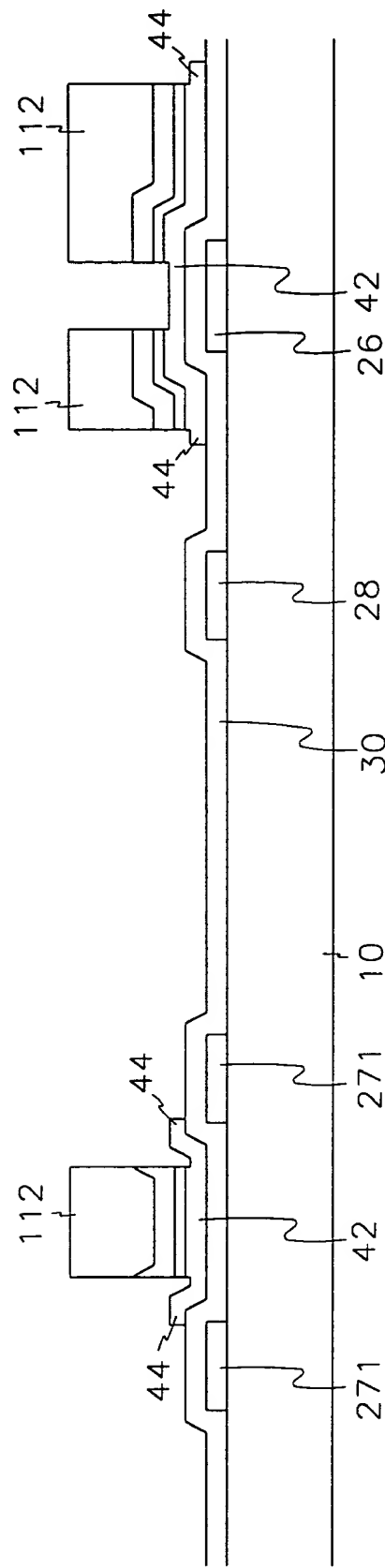


FIG.19A

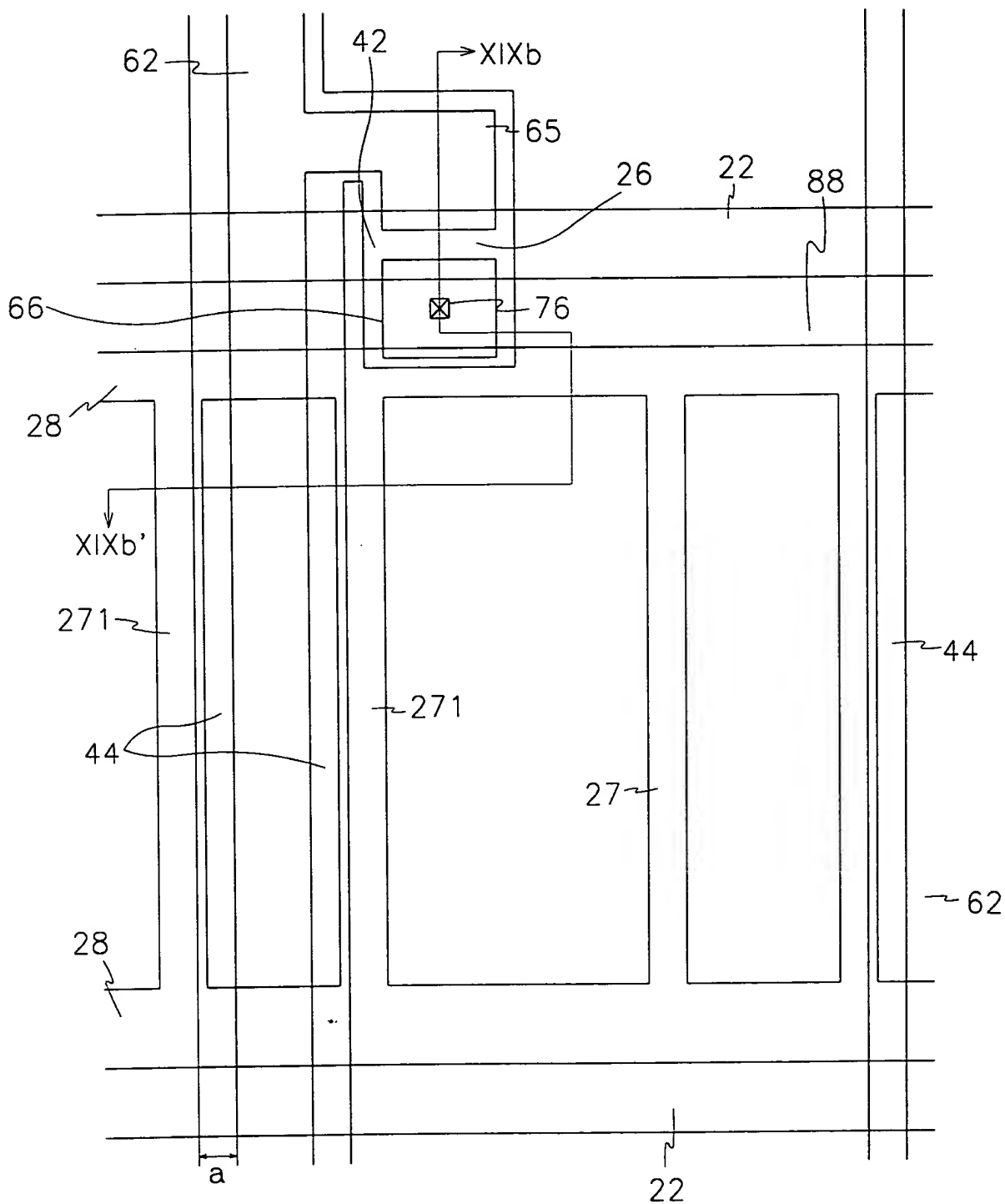


FIG. 19A

FIG. 19B

